

# MURHD560T4G, SURHD8560T4G, MURHD560W1T4G, SURHD8560W1T4G, SURHD8560T4G-VF01



ON Semiconductor®

[www.onsemi.com](http://www.onsemi.com)

## 600 V, 5 A Power Rectifier

### Features and Benefits

- Ultrafast 30 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 Volts
- SURHD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

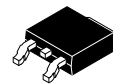
### Applications

- Power Supplies
- Inverters
- Free Wheeling Diodes

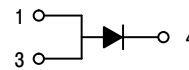
### Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 0.4 g (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
  - ◆ Machine Model = C (> 400 V)
  - ◆ Human Body Model = 3B (> 8000 V)

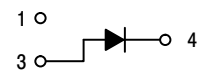
## ULTRAFAST RECTIFIER 5.0 AMPERES 600 VOLTS



DPAK  
CASE 369C  
STYLES 3, 8

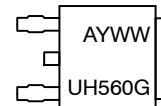


STYLE 3

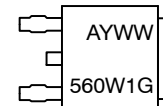


STYLE 8

### MARKING DIAGRAMS



STYLE 3



STYLE 8

UH560 = MURHD560T4  
560W1 = MURHD560W1T4  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejector pin), the front side assembly code may be blank.

### ORDERING INFORMATION

Device	Package	Shipping†
MURHD560T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SURHD8560T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
MURHD560W1T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SURHD8560W1T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SSURHD8560W1T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SSURHD8560T4G-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# MURHD560T4G, SURHD8560T4G, MURHD560W1T4G, SURHD8560W1T4G,

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	600	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 159^\circ\text{C}$ )	$I_{F(AV)}$	5.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	50	A
Operating Junction and Storage Temperature Range	$T_J$ , $T_{stg}$	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.5	$^\circ\text{C/W}$
Maximum Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	49.5	$^\circ\text{C/W}$

1. Rating applies when surface mounted on a 1.5 mm FR4 PC board with a 1 oz. thick, 700 mm<sup>2</sup> Cu area.

## ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) ( $I_F = 5.0$ Amps, $T_C = 25^\circ\text{C}$ ) ( $I_F = 5.0$ Amps, $T_C = 125^\circ\text{C}$ )	$V_F$	2.7 1.65	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_C = 25^\circ\text{C}$ ) (Rated dc Voltage, $T_C = 125^\circ\text{C}$ )	$I_R$	10 70	$\mu\text{A}$
Maximum Reverse Recovery Time ( $I_F = 1.0$ Amp, $di/dt = 50$ Amps/ $\mu\text{s}$ , $V_R = 30$ V, $T_J = 25^\circ\text{C}$ )	$t_{rr}$	30	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

MURHD560T4G, SURHD8560T4G, MURHD560W1T4G, SURHD8560W1T4G,

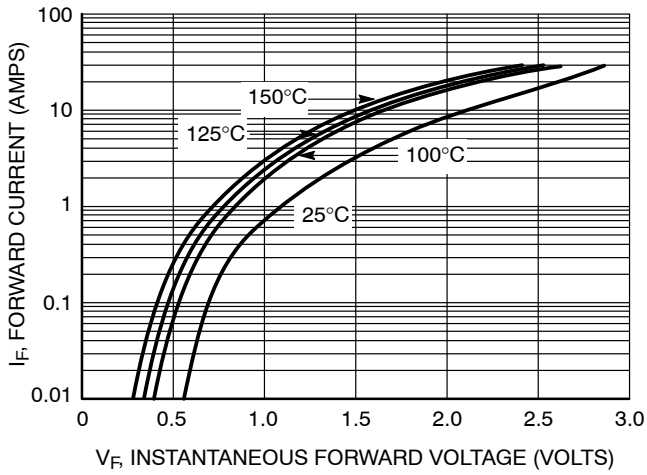


Figure 1. Typical Forward Voltage

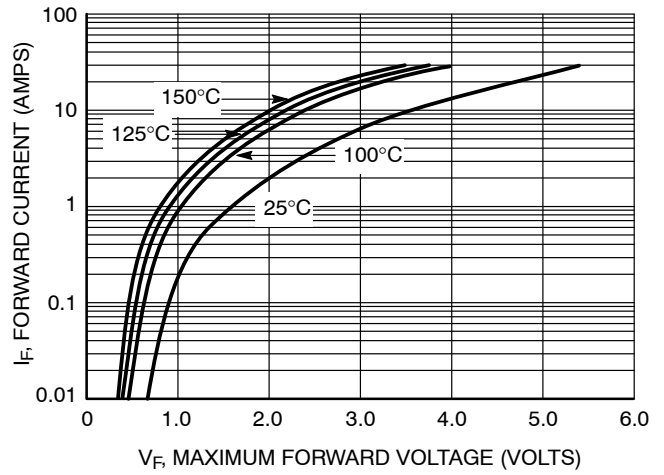


Figure 2. Maximum Forward Voltage

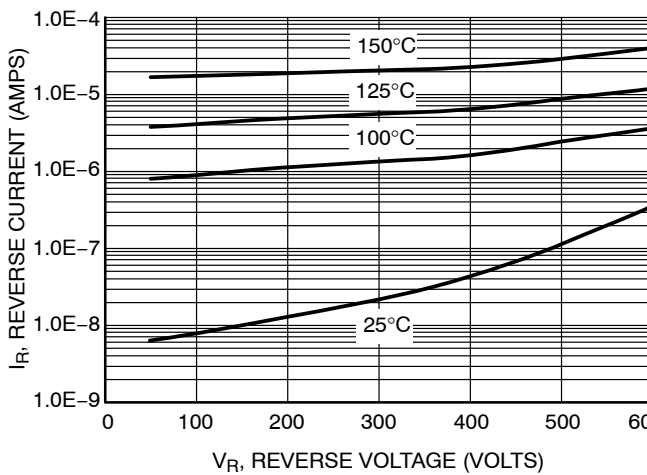


Figure 3. Typical Reverse Current

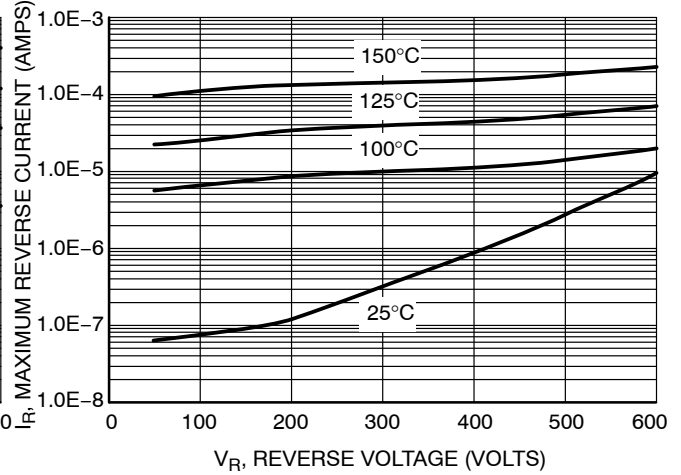


Figure 4. Maximum Reverse Current

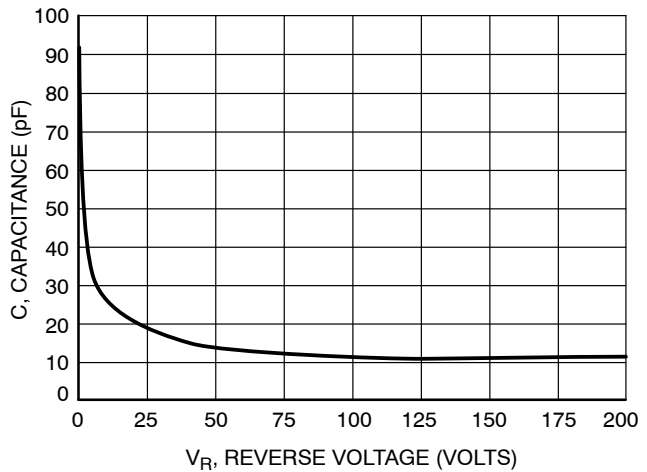


Figure 5. Typical Capacitance

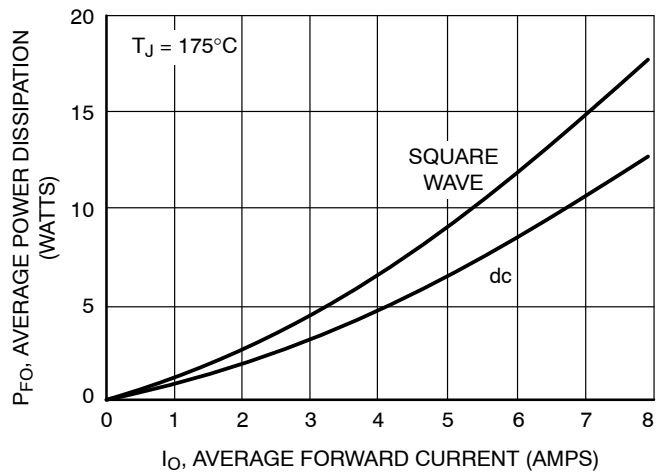


Figure 6. Forward Power Dissipation

MURHD560T4G, SURHD8560T4G, MURHD560W1T4G, SURHD8560W1T4G,

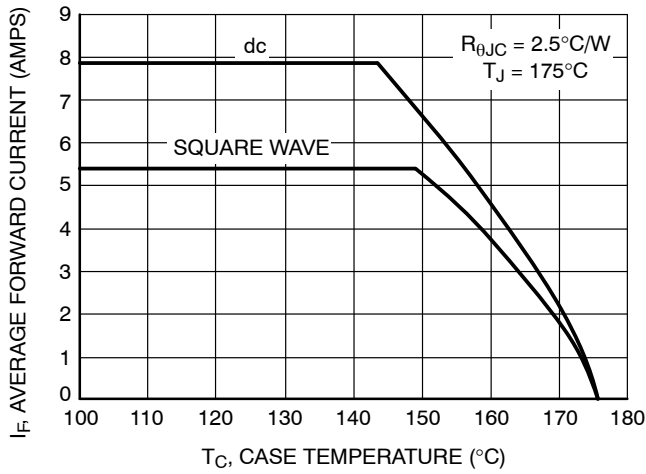


Figure 7. Current Derating

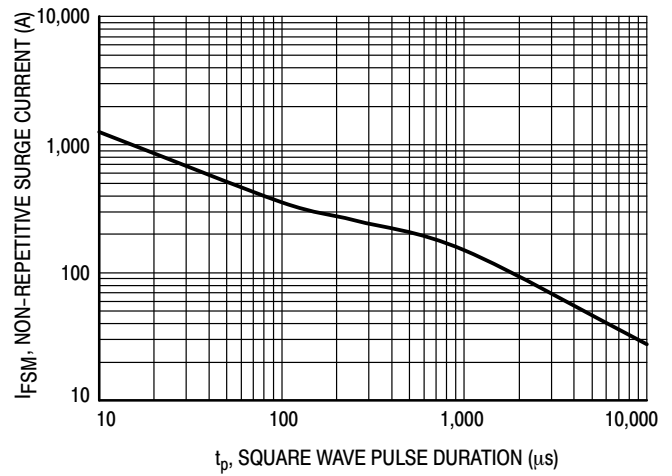


Figure 8. Typical Non-Repetitive Surge Current

\* Typical performance based on a limited sample size. ON Semiconductor does not guarantee ratings not listed in the Maximum Ratings table.

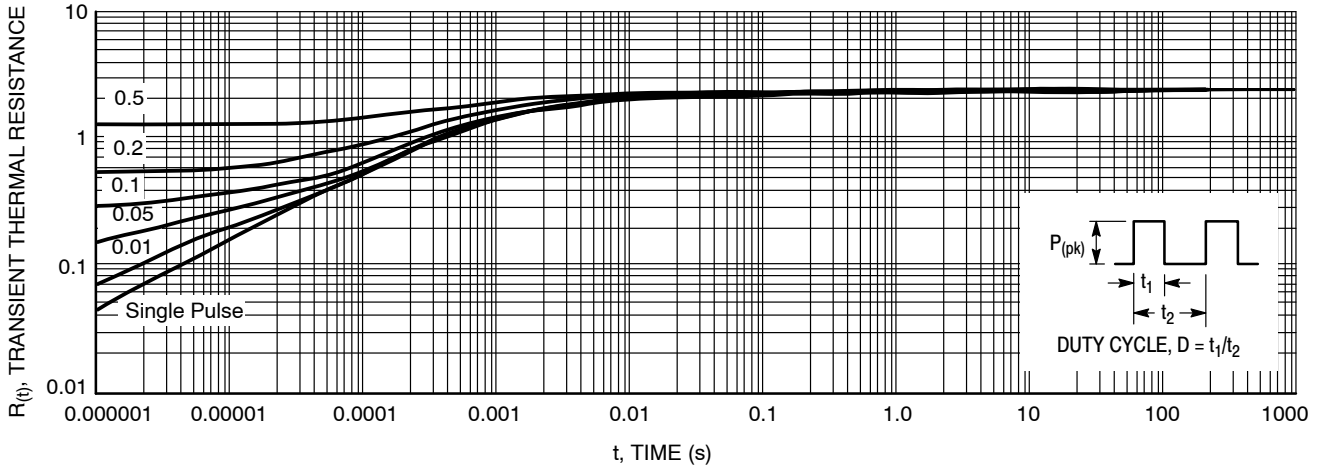


Figure 9. Thermal Response, Junction to Case

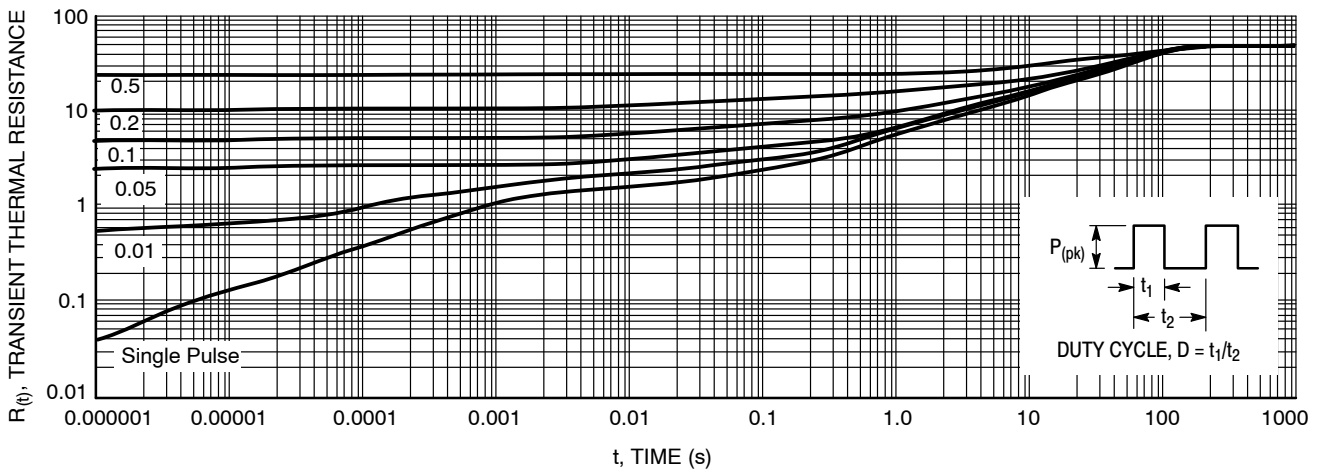


Figure 10. Thermal Response, Junction to Ambient

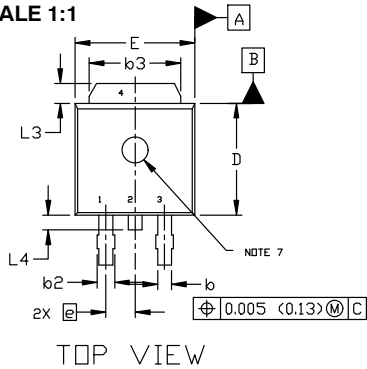
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



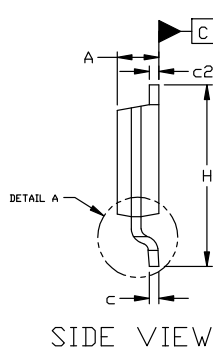
## DPAK (SINGLE GAUGE) CASE 369C ISSUE G

DATE 31 MAY 2023

SCALE 1:1



TOP VIEW

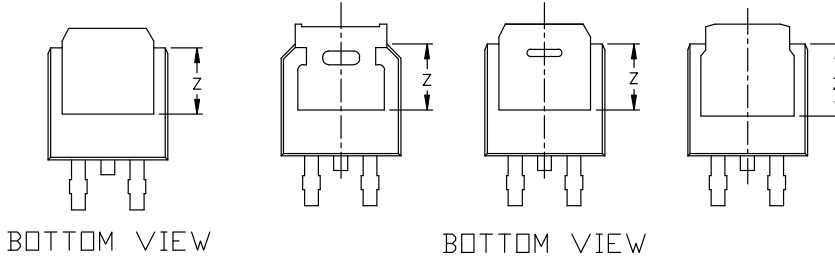


SIDE VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

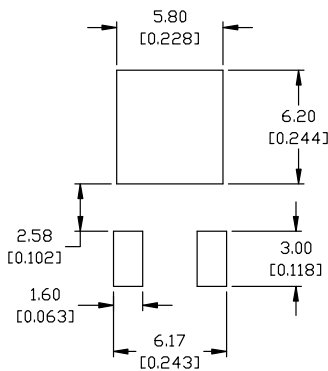
DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	----	0.040	---	1.01
Z	0.155	----	3.93	---



BOTTOM VIEW

BOTTOM VIEW

ALTERNATE CONSTRUCTIONS

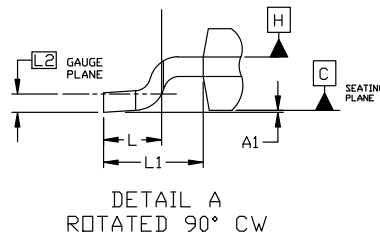


### RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SLDERRM/D.

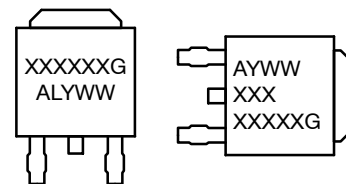
- |  |   |   |  |  |
|--|---|---|--|--|
| <b>STYLE 1:</b><br>PIN 1. BASE<br>2. COLLECTOR<br>3. EMITTER<br>4. COLLECTOR | <b>STYLE 2:</b><br>PIN 1. GATE<br>2. DRAIN<br>3. SOURCE<br>4. DRAIN | <b>STYLE 3:</b><br>PIN 1. ANODE<br>2. CATHODE<br>3. ANODE<br>4. CATHODE | <b>STYLE 4:</b><br>PIN 1. CATHODE<br>2. ANODE<br>3. GATE<br>4. ANODE | <b>STYLE 5:</b><br>PIN 1. GATE<br>2. ANODE<br>3. CATHODE<br>4. ANODE |
|--|---|---|--|--|

- |  |  |   |   |  |
|--|--|---|---|--|
| <b>STYLE 6:</b><br>PIN 1. MT1<br>2. MT2<br>3. GATE<br>4. MT2 | <b>STYLE 7:</b><br>PIN 1. GATE<br>2. COLLECTOR<br>3. EMITTER<br>4. COLLECTOR | <b>STYLE 8:</b><br>PIN 1. N/C<br>2. CATHODE<br>3. ANODE<br>4. CATHODE | <b>STYLE 9:</b><br>PIN 1. ANODE<br>2. CATHODE<br>3. RESISTOR ADJUST<br>4. CATHODE | <b>STYLE 10:</b><br>PIN 1. CATHODE<br>2. ANODE<br>3. CATHODE<br>4. ANODE |
|--|--|---|---|--|



DETAIL A  
ROTATED 90° CW

### GENERIC MARKING DIAGRAM\*



IC

Discrete

- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>DPAK (SINGLE GAUGE)</b>	<b>PAGE 1 OF 1</b>

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